Overview

HP 260 G3 Desktop Mini Business PC

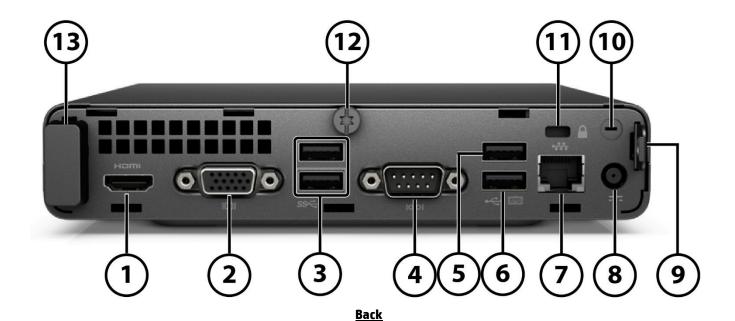


Front

- 1. (2) USB 3.1 Gen 1 (5 Gbits/s data speed)
- 2. Combo Microphone/Headphone Jack
- 3. Hard drive activity light
- 4. Dual-state power button



Overview



- 1. HDMI 1.4
- 2. VGA
- 3. (2) USB 3.1 Gen 1 ports (5 Gbits/s data speed)
- 4. Serial port
- 5. (1) USB 2.0 ports
- 6. (1) USB 2.0 ports (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)
- 1. Must be configured at time of purchase

- 7. RJ45 network connector
- 8. Power connector
- 9. Padlock loop
- 10. External WLAN antenna opening 1
- 11. Cable lock slot
- 12. Cover release thumbscrew
- 13. Internal WLAN antenna cover

Overview

AT A GLANCE

- 7th Generation Intel® processors (up to Core™ i5)¹, featuring integrated Intel® HD Graphics
- Choice of Windows 10 Home, Windows 10 Professional, and FreeDOS 2.0
- Up to 32GB of DDR4 Synchronous Dynamic Random Access Memory (SDRAM)
- Optional M.2 PCIe NVMe solid state drives (SSD) enabling faster system startup and application launches
- Support for up to two monitors via two standard HDMI 1.4 and VGA connectors
- Serial port support comes standard enabling support for legacy peripherals
- Integrated Realtek RTL8111HSH-CG Gigabit Network Connection
- Optional Wi-Fi 802.11ac connectivity
- Integrated HD audio featuring Conexant CX20632
- Trusted Platform Module (TPM) 2.0
- VESA mounting incorporated into chassis design
- Dust filter available for Desktop Mini
- High efficiency energy saving power supply
- ENERGY STAR® certified. EPEAT® Silver registered where applicable/supported. Registration may vary by country.
 See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options
- PC chassis and all internal components and modules are manufactured with low halogen content²
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support

2. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



^{1.} Multi core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance

Standard Features and Configurable Modules

OPERATING SYSTEMS

Preinstalled (Windows)

Windows® 10 Pro 64 ¹ Windows® 10 Pro 64 (National Academic License) ^{1,2} Windows® 10 Home 64 ¹ Windows® 10 Home Single Language 64 ¹

Pre-installed (Other)

FreeDOS 2.0

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/
- 2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7

In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com

PROCESSOR

Intel® 7th Generation Core™ Processors

Intel® Core™ i5-7200U Processor¹
15W
2.5 GHz base frequency
Up to 3.1 GHz max. turbo frequency with Intel® Turbo Boost Technology²
3 MB cache, 2 cores, 4 threads
Intel® HD Graphics 620
Supports DDR4 memory up to 2133 MT/s data rate

Intel® Core™ i3-7130U Processor¹
15W
2.7 GHz base frequency
3 MB cache, 2 cores, 4 threads
Intel® HD Graphics 620
Supports DDR4 memory up to 2133 MT/s data rate

Intel® 7th Generation Pentium® Processors

Intel® Pentium® Gold 4415U Processor¹
15W
2.3 GHz base frequency
2 MB cache, 2 cores, 4 threads
Intel® HD Graphics 610
Supports DDR4 memory up to 2133 MT/s data rate



Standard Features and Configurable Modules

Intel® 7th Generation Celeron® Processors

Intel® Celeron® 3865U Processor¹
15W
1.8 GHz base frequency
2 MB cache, 2 cores, 2 threads
Intel® HD Graphics 610
Supports DDR4 memory up to 2133 MT/s data rate

1: Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

2. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

GRAPHICS

Integrated

Intel® HD Graphics 620 Intel® HD Graphics 610

NOTE: Intel® integrated HD Graphics varies by processor

MEMORY

Type

DDR4-2133 (Transfer rates up to 2133 MT/s)

Maximum

32 GB capacity

Memory Configurations

2 SODIMMs

4 GB (4 GB x 1)

8 GB (4 GB x 2)

8 GB (8 GB x 1)

16 GB (8 GB x 2)

16 GB (16 GB x 1)

32 GB (16 GB x 2)

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system. Memory modules support data transfer rates up to 2133 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate. **NOTE:** All memory slots are customer accessible / upgradeable.



Standard Features and Configurable Modules

STORAGE AND DRIVES

2.5 inch SATA Hard Disk Drives (HDD)

500GB 7200RPM 2.5in SATA HDD 1TB 7200RPM 2.5in SATA HDD

2.5 inch Solid State Drives (SSD)

128GB 2.5in SATA Three Layer Cell SSD 256GB 2.5in SATA Three Layer Cell SSD

M.2 PCIe NMVe Solid State Drives (SSD)

128GB M.2 2280 PCIe NVMe SSD

256GB M.2 2280 PCIe NVMe SSD

128GB M.2 2280 PCIe NVMe Three Layer Cell SSD

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

NETWORKING/COMMUNICATIONS

Networking

Realtek RTL8111HSH-CG Gigabit Network Connection

Wireless¹

Realtek RTL8822BE 802.11ac 2x2 with Bluetooth® M.2 Combo Card Realtek RTL8821CE 802.11ac 1x1 with Bluetooth® M.2 Combo Card

1. Wireless access point and Internet service required and not included. Availability of public wireless access points limited.

AUDIO/MULTIMEDIA

HD audio with Conexant CX20632 Codec Combo Microphone/Headphone Jack



Standard Features and Configurable Modules

KEYBOARDS/POINTING DEVICES/BUTTONS AND FUNCTIONS KEYS

Keyboard

HP USB Business Slim Standalone Wired Keyboard HP USB Conferencing Wired Keyboard USB Wired Keyboard

Mouse

HP Optical Mouse
USB Hardened Mouse

NOTE: Availability may vary by country

PORTS

Internal slots and Ports

- (1) M.2 PCIe x1 2230 (for WLAN)
- (1) M.2 PCIe x4 2280/2230 Combo (for storage)
- (1) Desktop Mini SATA storage connector

Front I/O Ports

- (2) USB 3.1 Gen 1 ports
- (1) Microphone/Headphone Combo Jack

Rear I/O Ports

- (1) HDMI port
- (1) VGA port
- (1) Serial port
- (2) USB 3.1 Gen 1 ports
- (2) USB 2.0 ports

RJ45 network connector

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

BAYS

(1) 2.5" SATA Storage Drive Bay



Standard Features and Configurable Modules

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP ePrint + JetAdvantage 1

HP Hotkey Support

HP PhoneWise 2

HP Support Assistant 3

HP Velocity 4

HP Jumpstart

Buy Office (Sold separately)

Security Management

McAfee LiveSafe™ (1 year subscription) ⁴

- 1. HP ePrint Driver requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see www.hp.com/go/eprintcenter). Print times and connection speeds may vary.

 2. HP PhoneWise Client is only available on select platforms. For supported platforms and HP PhoneWise system requirements see
- 2. HP PhoneWise Client is only available on select platforms. For supported platforms and HP PhoneWise system requirements see http://www.hp.com/go/HPPhoneWise.
- 3. HP Support Assistant requires Windows and Internet access.
- 4. Availability may vary by country

POWER

Power Supply

External 65-watt power adapter



Standard Features and Configurable Modules

WEIGHT AND DIMENSIONS

System

Dimensions 6.97 x 6.89 x 1.35 in (177 x 175 x 34.2 mm)

Weight¹ 2.74 lbs (1.25 kg)

Volume 64 cu in

1.05 L

Packaging dimensions and weight

Dimensions 19.57 x 5.04 x 8.78 in (497 x 128 x 223 mm)

Weight 7.36 lbs (3.34 kg)

Palletization and Container

Type Air Shipment

Pallet Size 47.24 x 39.37 x 4.96 in

1200 x 1000 x 126 mm

Pallet Profile 1 unit/carton

18 cartons/layer

5 or 6 layers per pallet max depending on details of air freight 90 or 108 units per pallet depending on details of air freight

Pallet Size Loaded 47.24 x 39.37 x 57.64 in

1200 x 1000 x 1464 mm

1. Configured with 1 SATA Drive



Standard Features and Configurable Modules

UNIT ENVIRONMENT AND OPERATING CONDITIONS

Environmental and Industry

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 50° to 95° F (10° to 35° C)1

> Non-operating: -22° to 140° F(-30° to 60° C)

10% to 90% (non-condensing at ambient) **Relative Humidity** Operating:

> Non-operating: 0% to 95% (non-condensing at ambient)

Maximum Altitude (unpressurized) Operating: 10,000 ft (3048 m)

> 30,000 ft (9144 m) Non-operating:

CERTIFICATIONS

EPEAT® Silver1 WEEE (Waste, Electric and electronic equipment) **ENERGY STAR®** CEL

FCC

UL **RoHS**

1. EPEAT® registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options.



^{1.} Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

Standard Features and Configurable Modules

SERVICE AND SUPPORT

On-site Warranty¹: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day² service for parts and labor and complimentary limited technical support³. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack⁴. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.

- 1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 3. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 4. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications – Graphics

GRAPHICS

Intel® HD Graphics (integrated)¹

Output Connectors HDMI, VGA

Maximum Graphics Memory 32GB; however, system memory is allocated for graphics as needed using Intel's Dynamic Video

Memory Technology (DVMT), to provide an optimal balance between graphics and system

memory use.

Maximum Color Depth32 bits/pixelGraphics/Video API SupportDirectX 12
OpenGL 4.4



^{1.} All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Technical Specifications – Storage

STORAGE

500GB 7200RPM 2.5in SATA HDD

Capacity500GBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size16 MB

Logical Blocks 976,773,168 **Seek Time** 12 ms (Average)

 Height
 0.267 in/6.8 mm (nominal)

 Width
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)



Technical Specifications – Storage

1TB 7200RPM 2.5in SATA HDD

Capacity 1TB

Rotational Speed 7,200 rpm Interface SATA 6 Gb/s **Buffer Size** 32 MB

Logical Blocks 1,953,525,168 **Seek Time** 12 ms (Average)

0.374 in/9.5 mm (nominal) Height 2.75 in/70 mm (nominal) Width 41° to 131° F (5° to 55° C) **Operating Temperature**

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128GB 2.5in SATA Three Layer Cell SSD

Drive Weight <50q 128GB Capacity Height 7mm 100.45mm Length Width 69.85mm Interface SATA 3.0 (6Gb/s)

Performance Up to Random Read/Write = 70K/40K IOPS

Maximum Sequential Read Up to 530MB/s **Maximum Sequential Write** Up to 380MB/s **Logical Blocks** 250,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features DIPM; TRIM



Technical Specifications – Storage

256GB 2.5in SATA Three Layer Cell SSD

Drive Weight <62g
Capacity 256GB
Height 7mm
Length 100.45mm
Width 69.85mm
Interface SATA 3.0 (6Gb/s)

Performance Up to Random Read/Write = 55K/68K IOPS

Maximum Sequential ReadUp to 530MB/sMaximum Sequential WriteUp to 450MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features DIPM; TRIM

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</td>Capacity128GBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3

Performance Up to Random Read/Write = 60K/50K IOPS

Maximum Sequential ReadUp to 1400MB/sMaximum Sequential WriteUp to 395MB/sLogical Blocks250,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2



Technical Specifications – Storage

256GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10g
Capacity 256GB
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIE Gen3

Performance Up to Random Read/Write = 120K/170K IOPS

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 780MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight< 10g</th>Capacity128GBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3

Performance Up to Random Read/Write = 140K/40K IOPS

Maximum Sequential ReadUp to 2800MB/sMaximum Sequential WriteUp to 600MB/sLogical Blocks250,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2



Technical Specifications – Storage

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight< 10g</th>Capacity256GBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3

Performance Up to Random Read/Write = 150K/180K IOPS

Maximum Sequential ReadUp to 2700MB/sMaximum Sequential WriteUp to 1000MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2



Technical Specifications – Audio

HIGH DEFINITION AUDIO

Type Integrated

HD Stereo Codec Conexant CX20632

Audio I/O Ports 1 Headset connector suppporing CTIA style headset

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

externally

Multi-streaming Capable Playback multi-streaming allows independent audio

streams to be sent to/from the front jacks and integrated speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1

kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes



Technical Specifications – Power Supply

POWER SUPPLY

Operating Voltage Range $90Vac\sim264Vac$ Rated Voltage Range $100Vac\sim240Vac$ Rated Line Frequency $50Hz\sim60Hz$ Operating Line Frequency $47Hz\sim63Hz$ Rated Input Current $65W \le 1.7A$ Rated Input Current with $65W \le 1.7A$

Energy Efficient* Power Supply

Average efficiency 88% at 115V Average efficiency 89% at 230V

DC Output +19.5VV

Current Leakage (NFPA 99:

2102)

Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or

that contact patients in normal use. Per section 10.3.5.1.

Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care

facility or that contact patients in normal use. Per section 10.3.5.1.

Power cord length 6.0 ft. (1.83 m)



Technical Specifications – Networking and Communications

NETWORKING

Realtek RTL8111HSH-CG Gigabit Network Connection

Connector RJ-45

System Interface PCIe + SMBus

Data rates supported 10 Mbit/s operation (10BASE-T; IEEE 802.3; IEEE 802.3 clauses 13-14)

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s

IEEE Compliance IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE (Energy Efficient Ethernet)

Performance TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling Jumbo Frame 9K

Power consumption Cable Disconnetion: 25mW

100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW

Power ACPI compliant – multiple power modes

Management Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power consumption

Management Interface Auto MDI/MDIX Crossover cable detection

IT Manageability Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up

Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status



Technical Specifications – Networking and Communications

Realtek RTL8822BE 802.11ac 2x2 with Bluetooth® M.2 Combo Card

Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac		
Interoperability	Wi-Fi certified	Wi-Fi certified	
Frequency Bands	802.11b/g/n	• 2.402 – 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.	
	802.11a/n	 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 	
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz) 		
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security ³	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI 		
	1 Check latest software/dr	iver release for updates on supported security features.	
Network Architecture Models		Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming ²	IEEE 802.11 compliant roaming between access points		



Technical Specifications – Networking and Communications

Output Power ²	 802.11b: +14dBm minimum 802.11g: +12dBm minimum 		
	• 802.11a:+12dBm minimum		
	• 802.11n HT20(2.4GHz): +12dBn		
	• 802.11n HT40(2.4GHz): +12dBn	n minimum	
	• 802.11n HT20(5GHz) : +10dBm r	ninimum	
	• 802.11n HT40(5GHz) : +10dBm r	ninimum	
	• 802.11ac VHT80(5GHz): +10dBr	n minimum	
Power Consumption	Transmit mode2.0 W		
	Receive mode1.6 W		
	 Idle mode (PSP)180 mW(WLAN A 		
	 Idle mode50 mW(WLAN unassoc 	iated)	
	 Connected Standby 10mW 		
	Radio disabled8 mW		
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode		
Receiver Sensitivity ³	• 802.11b, 1Mbps : -93.5dBm max	imum	
	• 802.11b, 11Mbps : -84dBm maximum		
	 802.11a/g, 6Mbps : -86dBm max 	rimum	
	 802.11a/g, 54Mbps : -72dBm ma 	aximum	
	 802.11n, MCS07 : -67dBm maxir 	num	
	• 802.11n, MCS15 : -64dBm maxir	num	
	 802.11ac, MCS0: -84dBm maxin 	num	
	• 802.11ac, MCS9 : -59dBm maxin	num	
	3 Receiver sensitivity is measured at a packet error 10% for 802.11a/g (OFDM modulation).	rate of 8% for 802.11b (CKK modulation) and a packet error rate of	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm		
Weight	Type 2230 : 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating: Non-operating:	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating: Non-operating:	10% to 90% (non-condensing) 5% to 95% (non-condensing)	



Technical Specifications – Networking and Communications

Altitude	Operating: Non-operating:	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
HP Integrated Module with Blo	uetooth 4.0/4.1/4.2 Wireless Technology		
Bluetooth Specification	4.0/4.1/4.2 Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.		
Receiver Sensitivity Legacy			
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Electrical Interface	USB 2.0 compliant		
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software		
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension		



Technical Specifications – Networking and Communications

FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
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Realtek RTL8821CE 802.11ac 1x1 with Bluetooth® M.2 Combo Card

Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac		
Interoperability	Wi-Fi certified	Wi-Fi certified	
Frequency Band	802.11b/g/n	• 2.402 – 2.482 GHz NOTE: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.	
	802.11a/n	 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 	
Data Rates	802.11g: 6, 9,802.11a: 6, 9,802.11n: MCS	 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 	
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security ³	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i 		



Technical Specifications – Networking and Communications

	 Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI 		
	1 Check latest software/driver release for updates on supported security features.		
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)		
Roaming ²	IEEE 802.11 compliant roaming between access points		
Output Power ²	 802.11b: +14dBm minimum 802.11g: +12dBm minimum 802.11a: +12dBm minimum 802.11n HT20(2.4GHz): +12dBm minimum 802.11n HT40(2.4GHz): +12dBm minimum 802.11n HT20(5GHz): +10dBm minimum 802.11n HT40(5GHz): +10dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum 		
Power Consumption	 Transmit mode2.0 W Receive mode1.6 W Idle mode (PSP)180 mW(WLAN Associated) Idle mode50 mW(WLAN unassociated) Connected Standby 10mW Radio disabled8 mW 		
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode		
Receiver Sensitivity ³	 802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 		
	3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm		



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Weight	Type 2230 : 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating: Non-operating:	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating: Non-operating:	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating: Non-operating:	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
HP Integrated Module with Blu	etooth 4.0/4.1/4.2 Wireless Technology		
Bluetooth Specification	4.0/4.1/4.2 Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth component shall operate as a power of + 4 dBm for BR and EDR.	Class II Bluetooth device with a maximum transmit	
Receiver Sensitivity Legacy			
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Electrical Interface	USB 2.0 compliant		
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software		
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode		



Technical Specifications – Networking and Communications

LE Link Layer

LE Low Duty Cycle Directed Advertising

LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full

LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2

Headset Profile (HSP)

Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)



Technical Specifications – Networking and Communications

ENVIRONMENTAL

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT® Silver registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country.
- TCO certified

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".

Energy Consumption (in accordance with US **ENERGY STAR® test**

method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	4.5350	4.5700	4.3930
Normal Operation (Long idle)	4.0470	4.2030	3.9670
Sleep	0.3880	0.4210	0.3820
Off	0.3500	0.3880	0.3490

NOTE: Energy efficiency data listed is for an ENERGY STAR® certified product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® certified configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. Search keyword generator on HP's 3rd party option store for solar generator accessories at www.hp.com/go/options

Heat Dissipation*
Normal Operation (Short
idle)
Normal Operation (Long
idle)
Sleep

Off

115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
15.4644	15.5837	14.9801
13.8003	14.3322	13.5275
1.3231	1.4356	1.3026
1.1935	1.3231	1.1901

NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise
Emissions
(in accordance with
ISO 7779 and ISO 9296)
Typically Configured –
Idle
Fixed Disk – Random
writes

Longevity and Upgrading

Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)
3.1	20
4.4	33

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

Spare parts are available throughout the warranty period and or for up to 5 years after the end of production.

Technical Specifications – Networking and Communications

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight

Battery size: CR2032 (coin cell)

Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the silver level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 0% post-consumer recycled plastic (by wt.)
- This product is 95.1% recycle-able when properly disposed of at end of life.

Packaging Materials

Material Usage

External: PAPER/Corrugated

Internal: PLASTIC/Expanded Polyethylene - EPE

PLASTIC/Polyethylene low density - LDPE

The plastic packaging material contains at least 50% recycled content.

The corrugated paper packaging materials contains at least 70% recycled content.

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances



Technical Specifications – Networking and Communications

Packaging Usage

• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



After-Market Options (availability may vary by region)

<u>Type</u>	<u>Description</u>	<u>Part Number</u>
Display Bracket	HP B300 PC Mounting Bracket	2DW53A
	HP B500 PC Mounting Bracket	2DW52A
	HP Flat Panel Monitor Quick Release	EM870AA
Desktop Mini Accessories	HP Desktop Mini 500GB HDD/I/O Expansion Module	K9Q82AA
	HP Desktop Mini 65W Power Supply Kit	L2X04AA
	HP Desktop Mini DVD-Writer ODD Expansion Module	K9Q83AA
	HP Desktop Mini G3/G4 Port Cover Kit	1ZE52AA
	HP Desktop Mini I/O Expansion Module	K9Q84AA
	HP Desktop Mini LockBox V2	3EJ57AA
	HP Desktop Mini Security/Dual VESA Sleeve v2	2JA32AA
	HP Desktop Mini Vertical Chassis Stand	G1K23AA
	HP DM VESA Power Supply Holder Kit	1RL87AA
	HP G4 Mini 2.5-inch SATA Drive Bay Kit	3TK91AT
Graphics Options	HP HDMI Standard Cable Kit	T6F94AA
Security Hardware	HP Dual Head Keyed Cable Lock	T1A64AA
	HP Keyed Cable Lock 10mm	T1A62AA
Data Storage Drives	HP PCIe NVME TLC 256GB SSD M.2 Drive	1CA51AA
	Intel Optane 118GB M.2 SSD	4RV34AA
	Intel Optane Memory 16GB	1WV97AA
	HP 256GB SATA TLC Non-SED Solid State Drive	P1N68AA
Input Devices	HP Conferencing Keyboard	K8P74AA
	HP USB Business Slim Keyboard	N3R87AA
	HP USB Collaboration Keyboard	Z9N38AA
	HP USB Hardened Mouse	P1N77AA
	HP USB Mouse	QY777AA
Adapter	HP USB to Serial Port Adapter	J7B60AA
System Memory	HP 4GB DDR4-2666 SODIMM	3TK86AA
	HP 8GB DDR4-2666 SODIMM	3TK88AA
	HP 16GB DDR4-2666 SODIMM	3TK84AA
Multimedia Devices	HP Business Headset v2	T4E61AA
	HP USB Business Speakers v2	N3R89AA



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Change Log

Date of change:	Version History:		Description of change:
July 13, 2018	From v1 to v2	Update	EPEAT Gold updated to EPEAT Silver/Back image on call outs
			updated

